

Tflex™ B200 Thermal Gap Filler



PRODUCT DESCRIPTION

Tflex[™] B200 is a reliable, compliant thermal interface material offering good thermal performance and easier handling and features a range of multiple surface and enforcement options for a variety of applications. This gap filler's low modulus interface and softness relieves mechanical stress. It properly fills gaps, with tolerance to reduce thermal resistance.

Tflex[™] B200 helps absorb shock, resulting in improved device reliability over the long term. It has high dielectric insulation which works to protect against dielectric breakdown in or between devices. Tflex[™] B200 as a standard product is naturally tacky on both sides and requires no additional adhesive coating to inhibit thermal performance. The tack is designed to hold the pad in place during assembly and transport.

Tflex[™] B200MFG, an option featuring fiberglass in the middle, has strong tensile and both sides exhibit tackiness properties. This helps prevent deforming during manual or automated assembly.

Tflex[™] B200FG, a second option, has fiberglass enforcement located near one side. It offers a side difference, a higher deflection than the B200MFG option, and provides protection close to one side.

FEATURES AND BENEFITS

- Thermal Conductivity of 2W/m.K
- Compliant to application surfaces, long term reliability
- Shock resistance in automotive applications
- · Fiberglass enforcement, protection against breakthrough or deforming
- Protection with high DBV

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	
Color	Grey	Visual
Thickness	1mm~5mm(MFG, Standard)	
	0.5mm~5mm(FG)	
Thickness Tolerance	+/- 10%	
Thermal Conductivity (W/mK)	2	ASTM D5470
Density (g/cc)	2.2	Helium Pycnometer
Hardness (Shore 00)	42	ASTM D2240
Outgassing TML (weight %)	0.32	ASTM E595
Temperature Range	-40°C to 150°C	Laird Reliability Test
Rth@ 40 mils, 10 psi	1.10 °C–in2/W	ASTM D5470 (Modified)
UL Flammability Rating	V-0	UL 94
Volume Resistivity	2 x 10 ¹³ ohm-cm	ASTM D257

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AVAILABILITY

STANDARD THICKNESSES

- Standard B200, MFG options, 1.0 mm (0.040") to 5.0 mm (0.200") thick material available in 0.25mm (0.010") increments
- B200FG option, 0.5 mm (0.020") to 5.0 mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 18" x 18", and custom die cut part

PART NUMBER SYSTEM

Tflex[™] indicates Laird elastomeric thermal gap filler product line. B2xxx indicates Tflex[™] B200 product line with thickness in mils EXAMPLES:

• Tflex[™] B240 = 1000 microns / 0.040" thick material

Tflex B200 DS 190506

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